



IMAPS (INTERNATIONAL MICROELECTRONICS AND PACKAGING SOCIETY)

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2nd Micro/Nano-Electronics Packaging & Assembly, Design and Manufacturing Forum Conference & Exhibition

Call for Papers

Deadline January 13, 2012



2nd MiNaPAD Forum 2012

Grenoble, France

April 25-26, 2012



« *Bringing closer Design, Semiconductor, Assembly & Packaging communities* »

Abstracts are requested on the following topics (250 words min., one page max):

- Design: CAD and tools for IO placement for advanced packaging, design for reliability, IC and package co-design, opto & RF package design, thermal & mechanical modelling & simulations
- Innovative packaging for MEMS and emerging applications
- System-in-Package for smart systems, solving test and reliability challenges
- Process, test, reliability, characterization and challenges of advanced packaging platforms: 3D Packaging, fan-out WLP and embedded IC package
- Advanced interconnections: flip-chip for high IO count devices and sub 45nm CMOS, WLP metallurgies, bumping techniques

- Your submission must include the mailing address, business telephone number and email address and the content must be without commercial information . Address your abstract to imaps.france@imapsfrance.org
- Authors will be notified of paper acceptance with instructions for publication before February 9th, 2012
- Authors will be invited to submit a paper (no format) for proceeding publication (2 to 6 pages) before March 30th, 2012
- At the discretion of the program committee, submitted abstracts may be considered for poster presentation,
- Presentations conforming to the IMAPS template are due April 13th, 2012.

-Special student poster session : A poster session for students will address all of the above topics

-IEEE CMPT France chapter Best paper award : Co-authors will share an award for the best selected by the program committee

Partners

